

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent R_{DS(ON)}
- High Power and Current Handling Capability
- Green Device Available

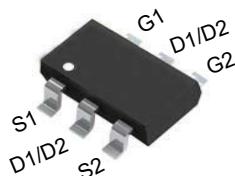
Product Summary



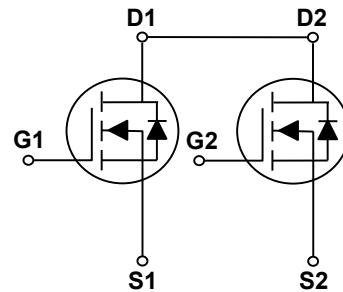
V _{DS}	20	V
I _D	7	A
R _{DS(ON)} (at V _{GS} =4.5V)	20	mΩ
R _{DS(ON)} (at V _{GS} =2.5V)	25	mΩ

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Battery Protection,Power Management
- Load Switch



SOT23-6L Top View



Absolute Maximum Ratings(T_A=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±10	V
Continuous Drain Current	I _D	7	A
Pulsed Drain Current ²	I _{DM}	25	A
Total Power Dissipation ³	P _D	1.25	W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	R _{θJA}	---	100	°C/W

20V Common-Drain Dual N-Channel MOSFET
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
Static Drain-Source On-Resistance ²	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}$, $I_D=4.5\text{A}$	---	14	20	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_D=3.5\text{A}$	---	19	25	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.5	0.7	1.2	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=18\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 10\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}$, $I_D=4.5\text{A}$	---	10	---	S
Total Gate Charge	Q_g	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=6\text{A}$	---	12	---	nC
Gate-Source Charge	Q_{gs}		---	2.3	---	
Gate-Drain Charge	Q_{gd}		---	1	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_G=6\Omega$, $I_D=1\text{A}$	---	10	---	ns
Rise Time	T_r		---	11	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	35	---	
Fall Time	T_f		---	30	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	900	---	pF
Output Capacitance	C_{oss}		---	220	---	
Reverse Transfer Capacitance	C_{rss}		---	100	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=1.7\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The power dissipation is limited by 150°C junction temperature

Typical Characteristics

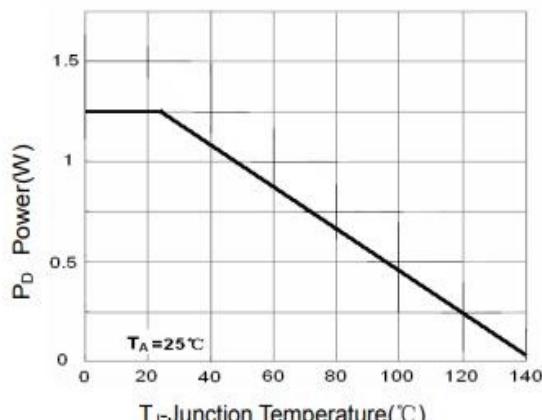


Figure 1 Power Dissipation

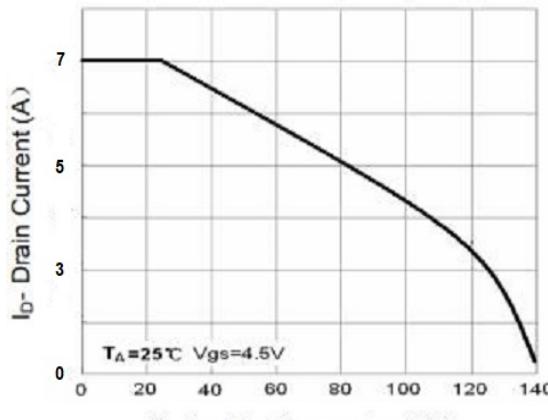


Figure 2 Drain Current

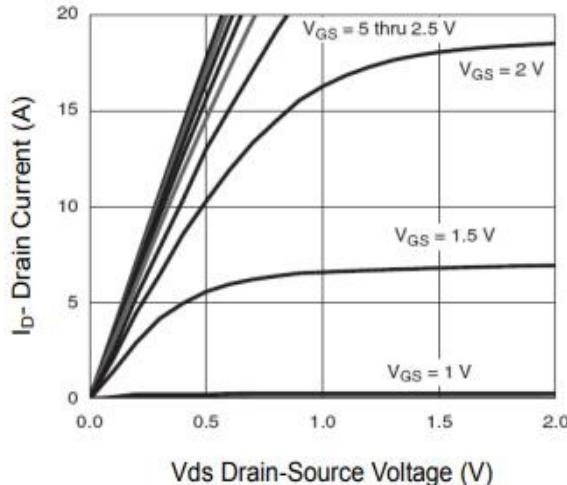


Figure 3 Output Characteristics

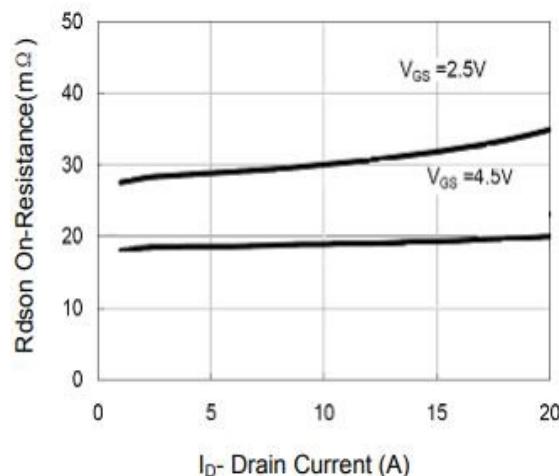


Figure 4 Drain-Source On-Resistance

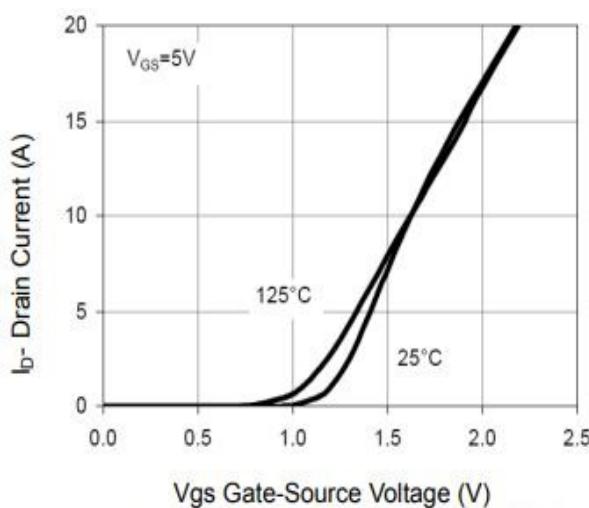


Figure 5 Transfer Characteristics

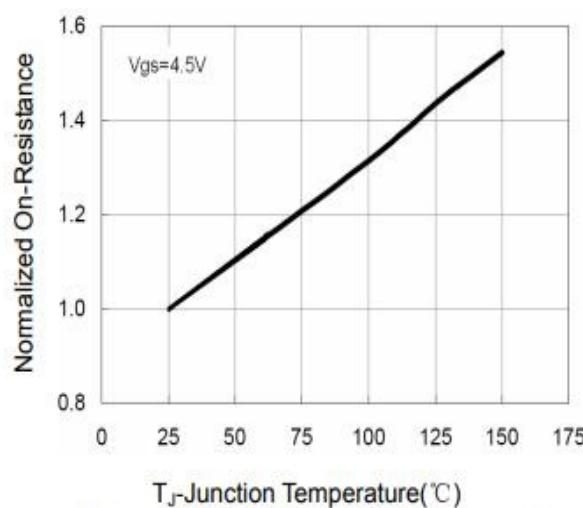
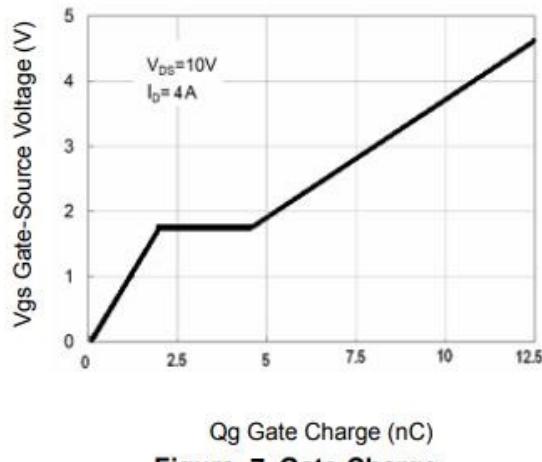
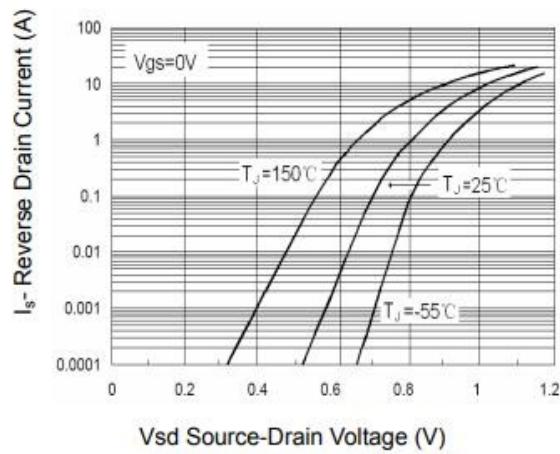
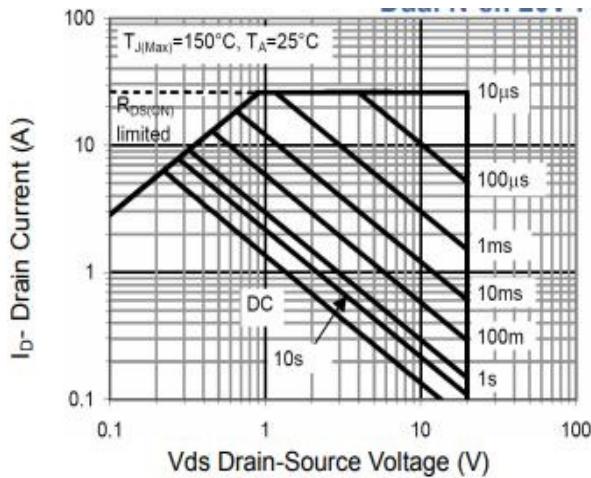
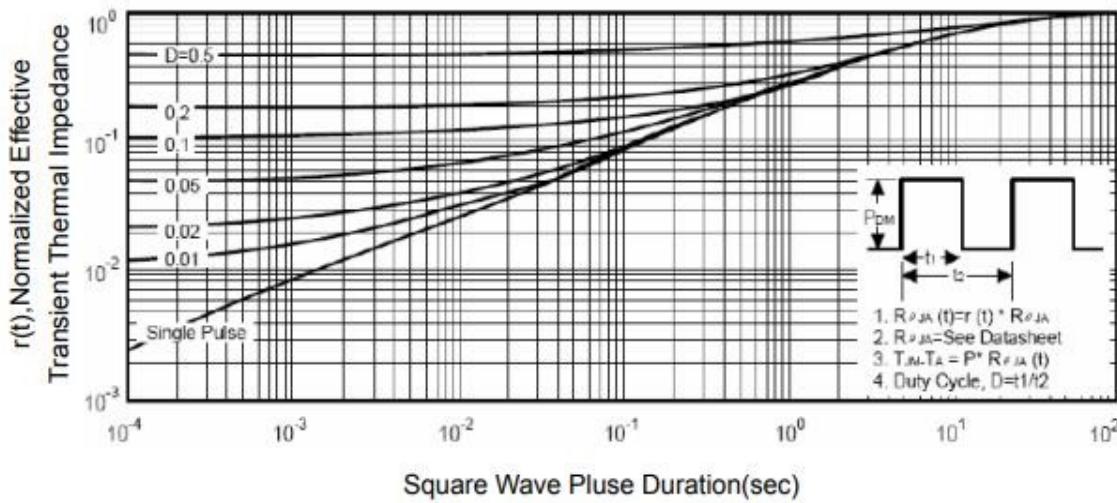
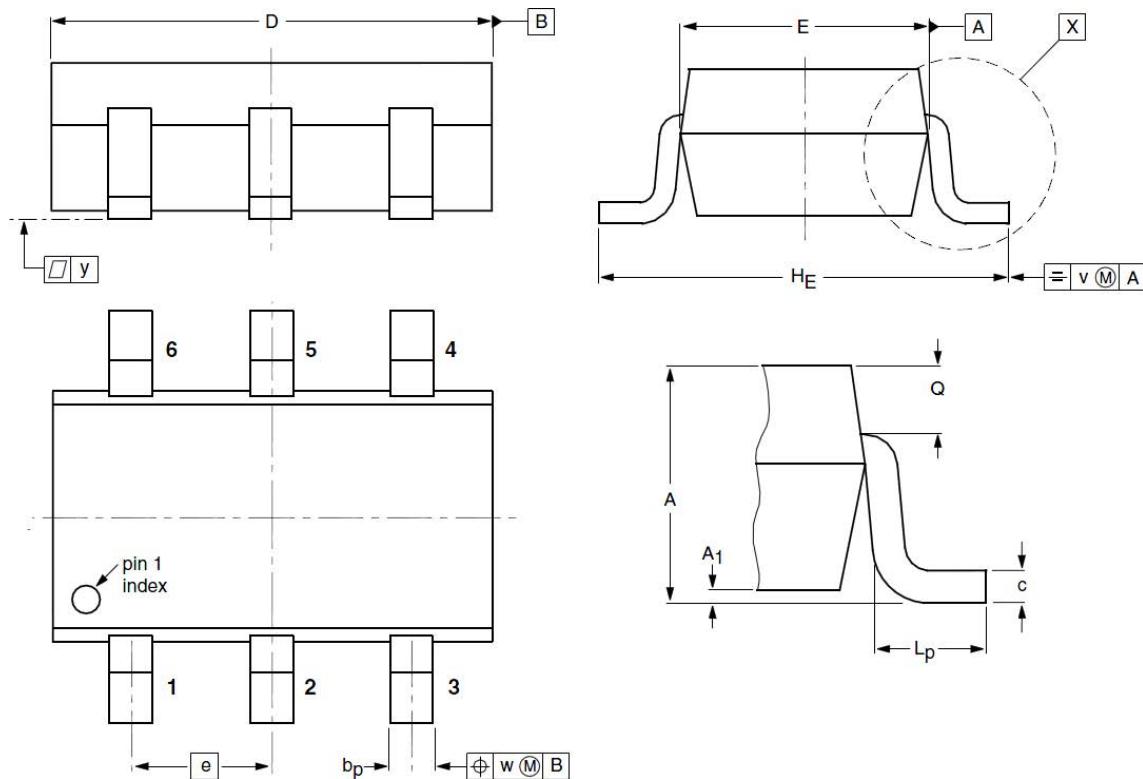


Figure 6 Drain-Source On-Resistance


Figure 7 Gate Charge

Figure 8 Source-Drain Diode Forward

Figure 9 Safe Operation Area

Figure 10 Normalized Maximum Transient Thermal Impedance

SOT23-6L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.45	A₁	0.01	0.05	0.15
b_p	0.30	0.40	0.50	c	0.10	0.15	0.22
D	2.70	2.92	3.10	E	1.35	1.55	1.75
e	--	0.95	--	H_E	2.50	2.80	3.00
L_p	0.30	0.45	0.60	Q	0.23	0.29	0.33
v	--	0.20	--	W	--	0.20	--
y	--	0.10	--				